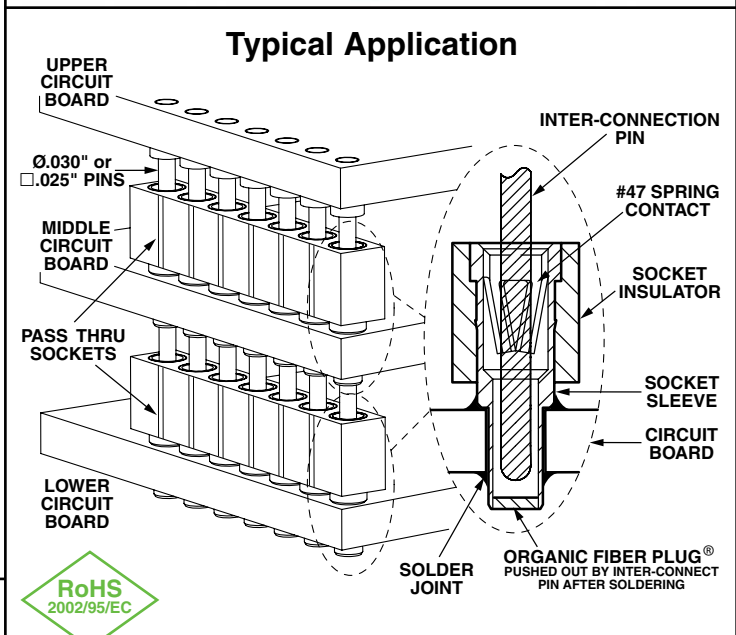
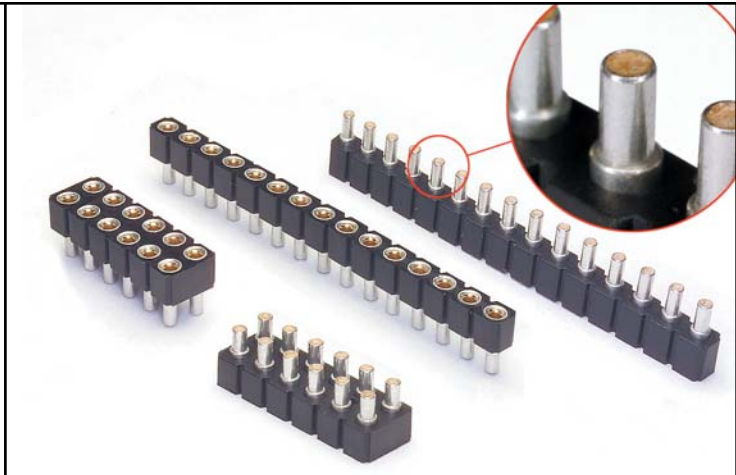
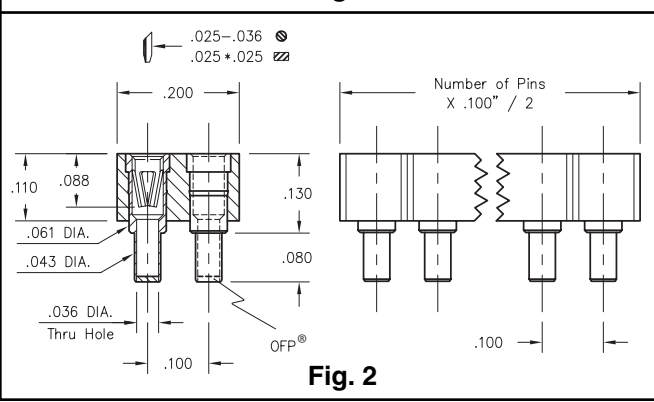
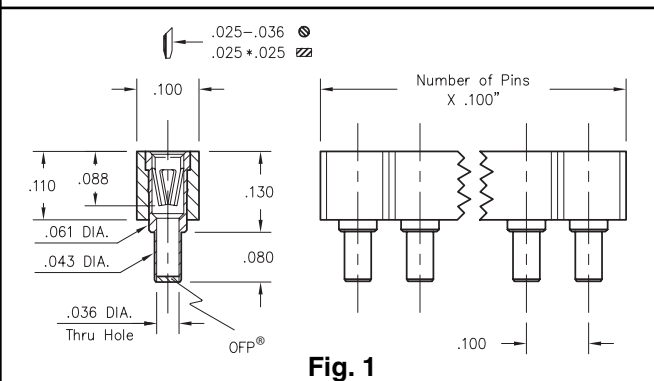


- 834/835 Series Pass Thru Sockets have a low .130" profile and will accept Ø.030" round pin, as well as industry standard .025" square pin headers.
- They are typically used to interconnect two or more parallel circuit boards.
- Sockets are designed for hand, wave or reflow* soldering. The high temp. insulator is compatible with all solder processes.
- Unique *ORGANIC FIBRE PLUG®* barriers prevent solder, paste or flux from contaminating the internal spring contacts. After soldering, the *OPF®* barriers are pushed out of the socket when the mating header is inserted.
- Mill-Max sockets use a precision machined brass sleeve with a press-fit beryllium copper "multi-finger" spring contact.
- Recommended mounting holes are Ø.046 ±.003" PTH (1,2 mm drilled prior to plating).

**Intrusive reflow (also called "pin-in-paste") is a technique of using conventional thru-hole components in a reflow soldering process. The pass thru socket is placed into plated-thru-holes in the circuit board (solder paste has previously been screen printed on pads adjacent to the holes) and the board is reflowed in the same pass as other SMT components. Solder will fill the plated-thru-holes and achieve solder joints as reliable as wave soldering. The OPF® barrier prevents solder paste from being picked-up inside the contact during assembly.*



US Patent #7,086,870



Ordering Information

Fig. 1	Single Row OPF® Pass Thru Socket	834-XX-0 -10-001000
	Specify # of pins	→ 01-64
Fig. 2	Double Row OPF® Pass Thru Socket	835-XX-0 -10-001000
	Specify # of pins	→ 02-72

For RoHS compliance select ◊ plating code.

XX= Plating Code
See Below

SPECIFY PLATING CODE XX=	13 ◊	93	99	43 ◊	44 ◊
Sleeve (Pin)	10µ" Au	200µ" Sn/Pb	200µ" Sn/Pb	200µ" Sn	200µ" Sn
Contact (Clip)	30µ" Au	30µ" Au	200µ" Sn/Pb	30µ" Au	200µ" Sn